



Initial Product/Process Change Notification

Document #: IPCN22935XA

Issue Date: 06 Jan 2020

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| Title of Change: | Qualification of ON Semiconductor Shenzhen, China as additional Manufacturing Site for Power Integrated Module (PIM) Products. | |
| Proposed First Ship date: | 06 Jul 2020 or earlier if approved by customer | |
| Contact Information: | Contact your local ON Semiconductor Sales Office or Way-Shan.Yong@onsemi.com | |
| PCN Samples Contact: | Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. | |
| Type of Notification: | This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com> | |
| Marking of Parts/ Traceability of Change: | No change in product marking | |
| Change Category: | Assembly Change | |
| Change Sub-Category(s): | Manufacturing Site Addition | |
| Sites Affected: | | |
| ON Semiconductor Sites | External Foundry/Subcon Sites | |
| ON Semiconductor Shenzhen, China | None | |
| Description and Purpose: | | |
| <p>This FPCN announces addition of assembly site for affected OPN list to increase capacity and manufacturing flexibility. The change is planned in adding additional ON Semiconductor site – ON Semiconductor Shenzhen, China. ON Semiconductor Shenzhen, China is a qualified assembly and test site for PIM module</p> <p>Upon the expiration of this PCN, OPNs in affected part list will be assemble/test at ON Semiconductor Shenzhen, China primarily. This product will be qualified to industrial requirements.</p> | | |
| | Before Change Description | After Change Description |
| Assembly Site | ON Semiconductor Seremban only | ON Semiconductor Shenzhen and/or ON Semiconductor Seremban |
| <p>There are no product material changes as a result of this change.</p> <p>There is no product marking change as a result of this change.</p> | | |

**Qualification Plan:**

QV DEVICE NAME : NXH160T120L2Q2F2S1G, SNXH80T120L2Q0P2G, NXH40B120MNQ0SNG and SNXH75M65L3F2STG

RRF : 64102, 64113, 64114, 64115, 64116, 64118 and 64120

PACKAGE : Q2PACK, Q0PACK, Q0BOOST and F2 OMRON

| Test | Specification | Condition | Interval |
|---------------|----------------------------------|---|--------------|
| TC | JESD22-A104 cond. G, soak mode 4 | - 40°C to 125°C, Temperature soak = 30 min, Transition time = 20 min max, Mandatory 100cyc | 100cyc |
| VVF | JESD22-B103 | - 25-500Hz/15min, 10G, each 2 hours X, Y, Z | Each 2 hours |
| Solderability | JESD22-B102 | - PbSn solder 215C, 5S, (precon 93C 8hr) | 5sec |
| | | - Pb free solder, 245C, 5S, (precon 93C 8hr) | 5sec |

Estimated date for qualification completion: 31 January 2020

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

| Part Number | Qualification Vehicle |
|---------------------|-----------------------|
| NXH100B120H3Q0PG | SNXH80T120L2Q0P2G |
| NXH100B120H3Q0SG | SNXH80T120L2Q0P2G |
| NXH160T120L2Q2F2S1G | NXH160T120L2Q2F2S1G |
| NXH160T120L2Q2F2SG | NXH160T120L2Q2F2S1G |
| NXH80B120H2Q0SNG | SNXH80T120L2Q0P2G |
| NXH80T120L2Q0S2TG | SNXH80T120L2Q0P2G |
| SNXH100M65L4Q2F2P2G | NXH160T120L2Q2F2S1G |
| SNXH80T120L2Q0P2G | SNXH80T120L2Q0P2G |
| NXH80B120H2Q0SG | SNXH80T120L2Q0P2G |
| SNXH75M65L3F2STG | SNXH75M65L3F2STG |
| NXH027B120MNF2PTG | SNXH75M65L3F2STG |
| NXH200T120H3Q2F2SG | NXH160T120L2Q2F2S1G |
| NXH25T120L2Q1PG | NXH160T120L2Q2F2S1G |
| NXH350N100H4Q2F2PG | NXH160T120L2Q2F2S1G |
| NXH350N100H4Q2F2SG | NXH160T120L2Q2F2S1G |



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|---------------------|---------------------|
| NXH40B120MNQ0SNG | SNXH80T120L2Q0P2G |
| NXH450B100H4Q2F2PG | NXH160T120L2Q2F2S1G |
| NXH450B100H4Q2F2SG | NXH160T120L2Q2F2S1G |
| NXH80B120MNQ0SNG | SNXH80T120L2Q0P2G |
| SNXH100B120H2Q0PG-N | SNXH80T120L2Q0P2G |